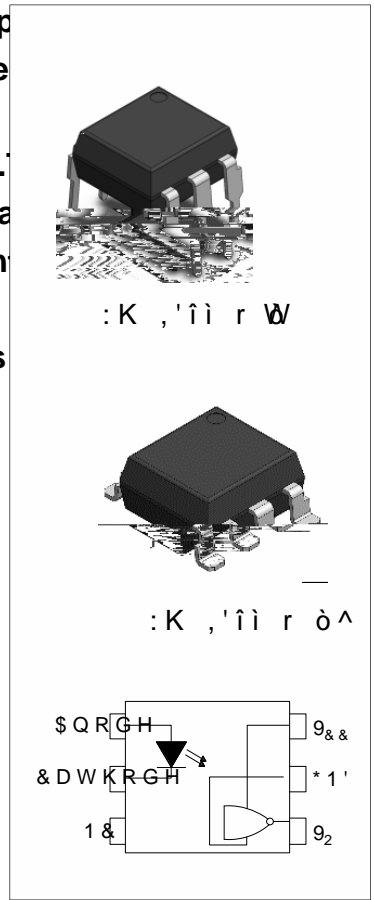




5 - o / k L t u L \ b

The products are 0.5MBd \ i [\ -speed opto-couplers in a p
 DIP6 pac _ a [e k it \ different lead in [options. T \ e device
 combines an AlGaAs infrared emitting diode as t \ e emitter
 k \ ic \ is optically coupled to a Sc \ mitt Tri [[er detector.
 products are k idely used in lo [ic isolator, pro [ram tea
 current level sensor, line receiv eliminate noise and transien
 problems, AC to TTL conversions e uare k ave s \ apin [, di [
 pro [rammin [of po k er supplies and interfaces computers
 perip \ erals.



a ° Lb C - ° u y k - o

Hi [\ isolation 5000 VRMS

Sc \ mitt tri [[er output

Operatin [temperate ran [e -40 š C to 110 š C

REACH / RoHS compliance

HBM: H3A / MM: M4 / CDM:C3

CEC approved

VDE approved

UL approved

° . o \ O y u - a ° Œ L a y a k i t e m p e r a t u r e 1 2 5 š C Ł

Parameter		Symbol	Value	Unit
Input	For k ard Current	I _F	50	mA
	Pea _ For k ard Current	I _{FP}	1 ⁷	\$
	5HYHUVH 9ROWDJH	9 ₅		
	,QSW 3RZHU 'LVVLSDWLRQ		3	P :
2XWSXW	6XSSO\ 9ROWDJH	9&&		
	2XWSXW 9ROWDJH	9 ₂		
	2XWSXW &XUUHQW	, ₂		
	2XWSXW 3RZHU 'LVVLSDWLRQ		3	P :
7RWDO 3RZHU 'LVVLSDWLRQ	3 _{WRW}			P :
,VRODWLRQ 9ROWDJH	9 _{LVR}		8	9UPV
2SHUDWLQJ 7HPSHUDWXUH	7 _{RSU}		a	

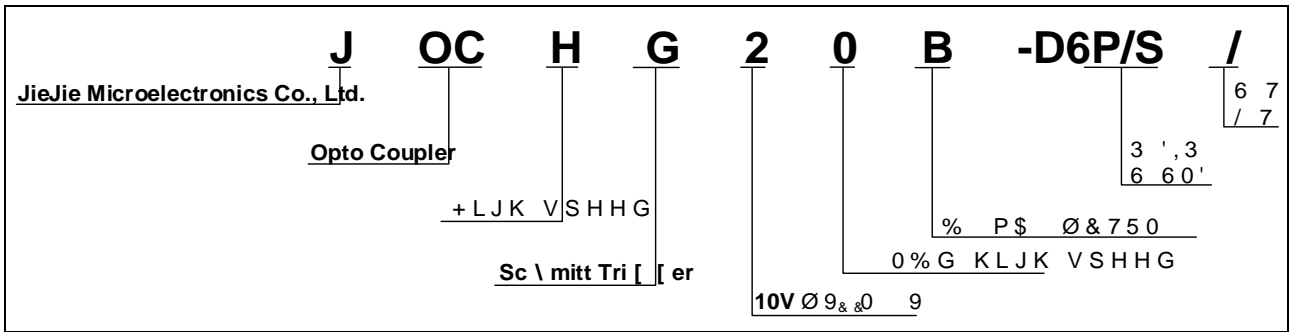
Junction Temperature	T_A	125	
6WRUDJH 7HPSHUDWXUH	T_{VWJ}	a	
6ROGHULQJ 7HPSHUDWXUH	T_{VRO}		

E K d í ì ì • % μ o • U í ì ì , ì (Æ ‹ μ v Ç
 E K d î () Æ í u] v μ š U Z X , X A ð ì • ò ì 9

> d Z / > , Z d Z / Temperature 125 š C Ł

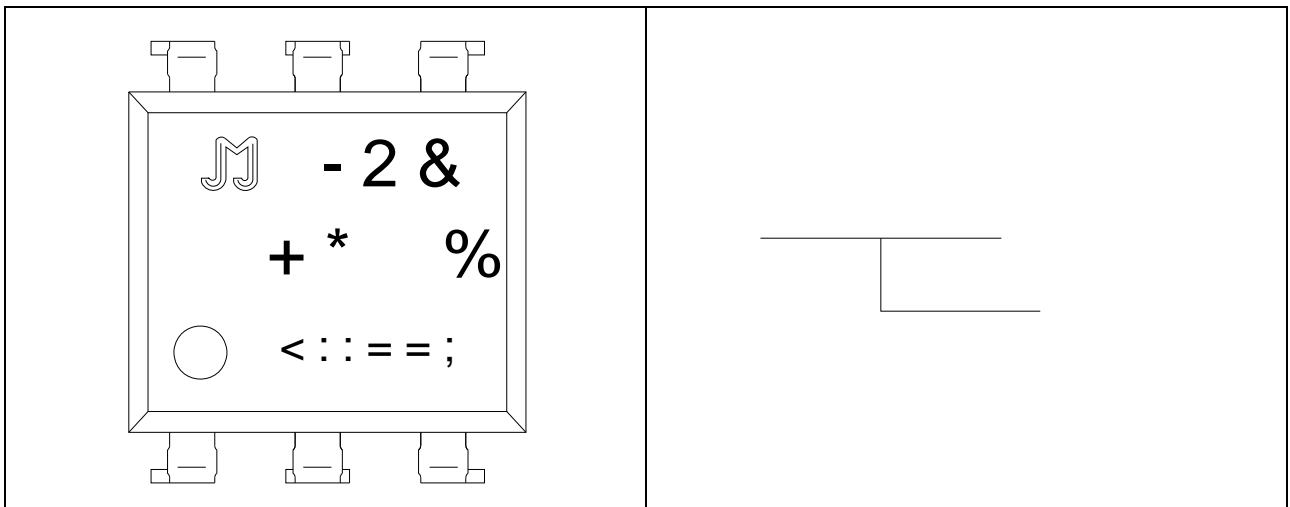
Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage [e	V_F	$I_F 10mA$	-	1.35	1.6	V
	Reverse Current	I_R	V				

\ k5 - kLbD LbC \ ka ° uL \ b



W I]vP Yμ vš]šÇ	
K%o š]}v	Yμ vš]šÇ
/W	òì hv]š•ldμ
^D	íîìì hv]š•lZ o

D Z < / E'



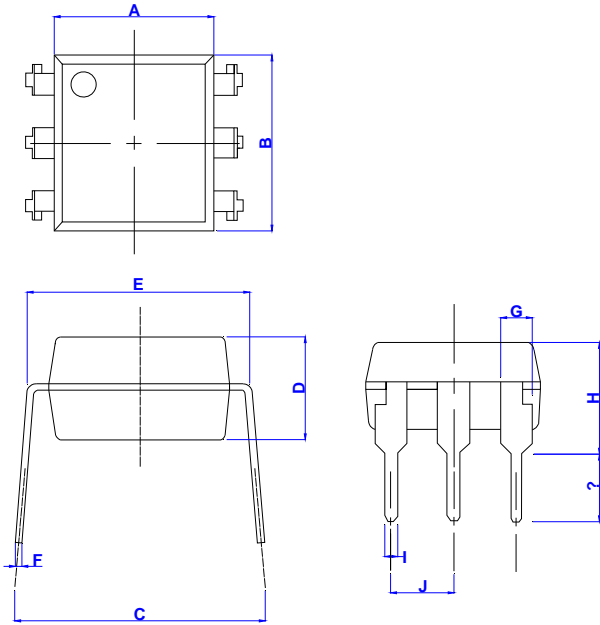
/
FIG.1:

/

t 5

y

Standard DIP Type:



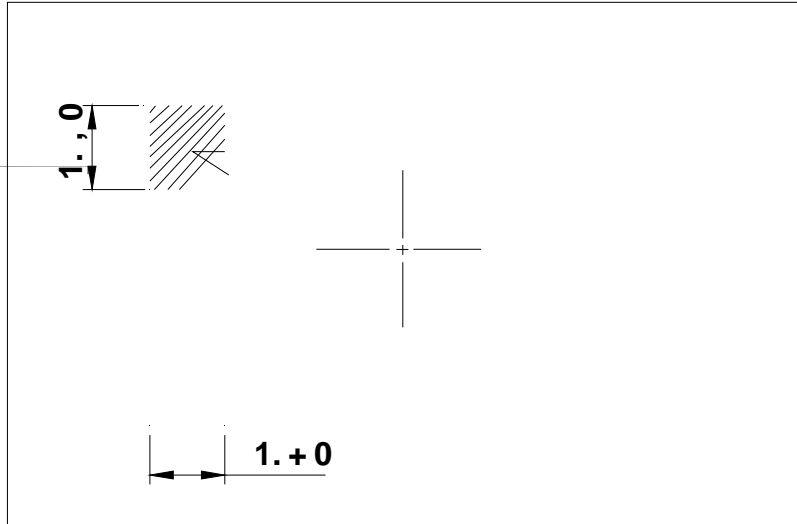
Ref.	Dimensions					
	Millimeters			Inc \ es		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	6. - 2		+ .32	0.2 + 2		0.2 , ,
C	+ .15		, . - 5	0.2 , 1		0.352
D	3.20		3.60	0.126		0.142
E	+ .32		+ . - 2	0.2 , ,		0.312
F	0.15		0.35	0.006		0.014
G	1.15		1.35	0.045		0.053
H	3. - 0		4.50	0.154		0.1 + +
I	0.40		0.60	0.016		0.024
J	2.2 -		2. + -	0.0 - 0		0.110
?	2.24		3.24	0.0 , ,		0.12 ,

Option SMD Type:

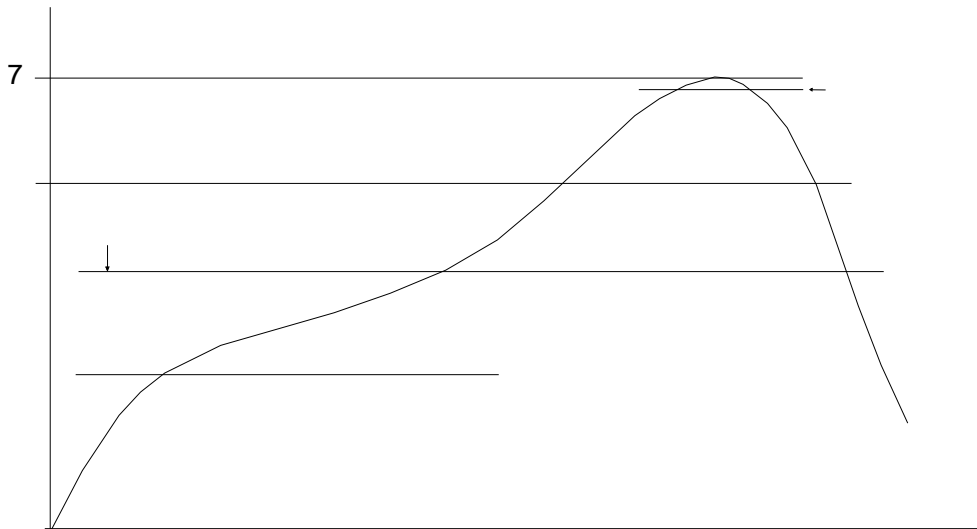
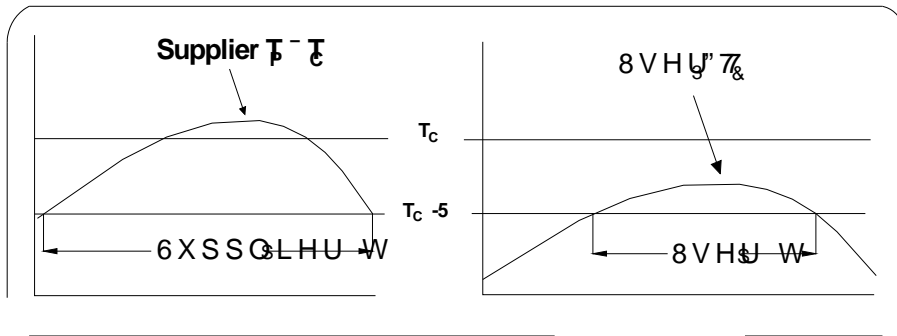
Ref.	Dimensions					
	Millimeters			Inc \ es		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	6. - 2		+ .32	0.2 + 2		0.2 , ,
C	- .50		10.50	0.3 + 5		0.413
D	3.20		3.60	0.126		0.142
E	+ .32		+ . - 2	0.2 , ,		0.312
F						
G						
H						
I	0. - 0		1.50	0.035		0.05 -
J	3.30		3. - 0	0.130		0.154
?						

k - / \ aa - b5 - 5 o \ O5 - k a ° o M 5

Option SMD



k - CO \ ‡ LbC \ ka ° uL \ b



Note:

1. Reflow soldering is recommended at the temperatures and time, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component is cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component is a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0 to 40 °C /
Recommend storage humidity: 0 to 60% /
MSL level: MSL 1